



Docket No. 0039-7292-2 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: KAORI UMEZAWA, ET AL.

GAU: 2814

SERIAL NO: 09/358,388

EXAMINER: MAI, ANH D

CPA FILED: NOVEMBER 20, 2000

FOR: SUBSTRATE HAVING SHALLOW TRENCH ISOLATION AND METHOD OF...

REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

This is a request for Continued Examination (RCE) under 37 C.F.R. §1.114 of the above-identified application.

Submission required under 37 C.F.R. §1.114

Previously Submitted:

- ☐ Consider the amendment(s)/reply under 37 C.F.R. §1.116 previously filed on
- ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on

Enclosed:

- ☒ Amendment with Marked-up Copy
- ☐ Information Disclosure Statement (IDS)
- ☒ Other: PETITION FOR EXTENSION OF TIME (1 MONTH)

RECEIVED
APR 23 2002
TECHNOLOGY CENTER 2300

FEES	RATE	CALCULATIONS
<input type="checkbox"/> Suspension of action on the above-identified application is requested under 37 C.F.R. §1.103(c) for a period of months.	\$130.00	\$0.00
<input checked="" type="checkbox"/> RCE Fee required under 37 C.F.R. §1.17(e)	\$740.00	\$740.00
<input type="checkbox"/>		
<input type="checkbox"/>		\$0.00
TOTAL OF ABOVE CALCULATIONS:		\$740.00
<input type="checkbox"/> REDUCTION BY 50% FOR FILING AS SMALL ENTITY		\$0.00
TOTAL:		\$740.00

- ☒ A check in the amount of **\$850.00** is enclosed

- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 CFR 1.136, and any additional fees required under 37 CFR 1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate of this sheet is enclosed.



22850

Customer Number 22850
Tel. (703) 413-3000
Fax. (703) 413-2220

Respectfully Submitted,

OBLON, SPIVAK, MCLELLAND,
MAIER & NEUSTADT, P.C.

Gregory J. Maier

Registration No. 25,599

Raymond F. Cardillo, Jr.

Registration No. 40,440

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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

#26/E
4-30-2
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IN RE APPLICATION OF:

KAORI UMEZAWA ET AL.

SERIAL NO: 09/358,388

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FOR: SUBSTRATE HAVING SHALLOW
TRENCH ISOLATION AND
METHOD OF MANUFACTURING
THE SAME

: GROUP ART UNIT : 2814

: EXAMINER: MAI

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AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Responsive to the Official Action mailed July 18, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claim 47 without prejudice or disclaimer.

Please amend claims 9, 10, 25-29, 36, and 45 as shown in the attached marked-up copy to read as follows:

9. (Four times amended) A method of manufacturing a semiconductor substrate having shallow trench isolation regions and a device region sandwiched by the shallow trench isolation regions, comprising:

(a) forming a plurality of grooves on part of a surface of the semiconductor substrate, each of grooves having a width narrower than $0.5\mu\text{m}$;